

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	19	"5702775"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:11
L2	5	("4645551"   "5150438"   "5294487"   "5410789"   "5593721").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/21 11:36
L3	185127	(saw (surface near acoustic near wave))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:43
L4	12311	3 and ("poly-ethylene" polyethylene "poly-propylene" polypropylene (acrylonitrile near polymer) "poly-urethane" polyurethane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:44
L5	5990	4 and (heating heated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L6	2495	5 and ((volume near (changing changed)) shrink\$3 expand\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L7	1296	6 and (sealing sealed encapsulant encapsulated encapsulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L8	869	7 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:46

## EAST Search History

L9	423	8 and (package packaging)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:46
L10	421	9 and (method process)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:35
L11	322	10 and (chip die ic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:57
L12	58	428/1.62.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:45
L13	345	310/340.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:39
L14	4	4 and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:45
L15	3587	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:05
L16	0	11 and 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 15:57

## EAST Search History

L17	36	11 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:11
L18	286	11 not 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:39
L19	3797	428/40.1,76.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:40
L20	61	3 and 19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:40
L21	26	20 and ((volume near (changing changed)) shrink\$3 expand\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:42
L22	0	21 and (surface near1 wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:42
L23	2709	3 and (surface near1 wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 17:06
L24	509	23 and ((volume near (changing changed)) shrink\$3 expand\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:42

## EAST Search History

L25	3	24 and (volume near (changing changed))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:43
L26	4	(surface near acoustic near wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:43
L27	1174	(surface near1 wave) and ("poly-ethylene" polyethylene "poly-propylene" polypropylene (acrylonitrile near polymer) "poly-urethane" polyurethane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L28	531	27 and (heating heated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L29	220	28 and ((volume near (changing changed)) shrink\$3 expand\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L30	124	29 and (sealing sealed encapsulant encapsulated encapsulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:45
L31	87	30 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:46
L32	48	31 and (package packaging) and (chip die ic semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 16:46

## EAST Search History

L33	137	yoshikawa-yoshishige.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 17:06
L34	0	33 and (surface near1 wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 17:07
L35	3	33 and ((surface near1 wave) saw)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 17:07